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Remarks

Applicants appreciate the prompt and complete examination given.

Claims 1-7 and 21 were rejected under 35 U.S.C 102(b) as unpatentable over Inuoe, et al, U.S. Pat. No. 5,180,627. Applicants respectfully traverse the rejection.

Claims 1 and 21 are amended to recite the adhesive composition for bonding an elastomer to a substrate consists essentially of the film former and crosslinker, and which include the feature originally presented of reactivity with the elastomer to chemically couple the elastomer to the adhesive. These claims are interpreted to be absent an epoxy and hardening agent, which is essential in the adhesive disclosed in Inuoe, et al. See SUMMARY in U.S. Pat. No. 5,180,627. Moreover, Inuoe et al do not disclose an adhesive that is coupled to an elastomer. The Inuoe, et al disclosure pertains to bonding heat resistant films to circuit boards. A representative heat resistant film is a polyimide, which is not an elastomer within the meaning provided in the instant specification. Heat resistant films bear no resemblance to the elastomers as defined by the present invention.

There is no suggestion in Inuoe et al to modify the heat resistant adhesive by removal of the epoxy and hardening agent. There is no motivation since a curable epoxy resin is critical in obtaining heat resistance. It is essential to the Inuoe, et al adhesive also in that it is a liquid carrier at ambient temperature in order to form an adhesive film. Removal of the liquid epoxy and curative would render the adhesive of Inuoe, et al inoperative. Applicants submit that patentable subject matter is now presented, and earnestly await an indication of allowance.

Respectfully submitted,

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CERTIFICATE OF MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited on the date indicated below with the United States Postal Service in an envelope addressed to the Assistant Commissioner of Patents, Washington, DC 20231, with sufficient postage as first class mail (37 CFR 1.8(a)).

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(Signature of person mailing paper)

July 2, 2003
Date mailed